

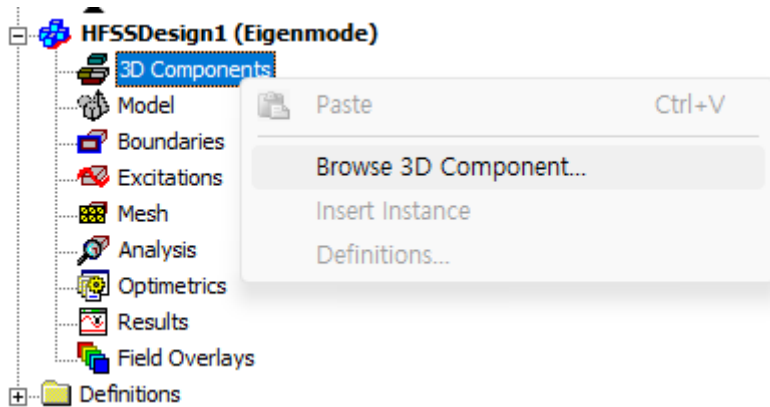
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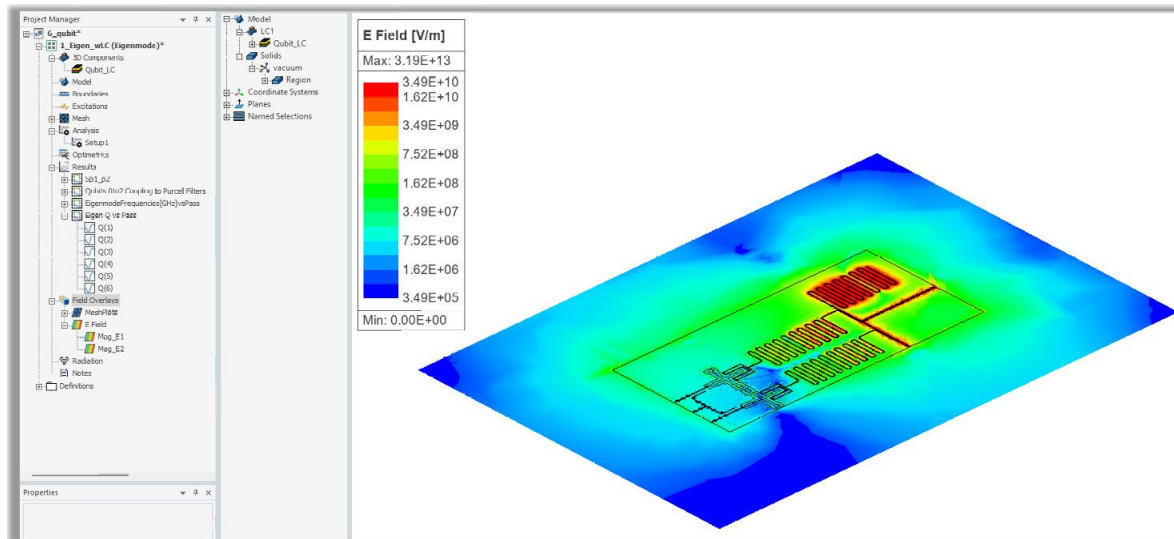
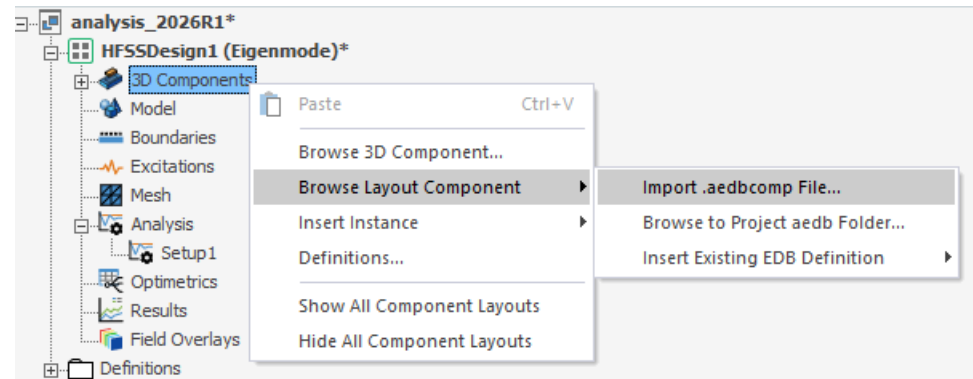
## 2026 R1 추가 기능

- ✓ Layout Component 공진 모드 해석 지원

2025R2

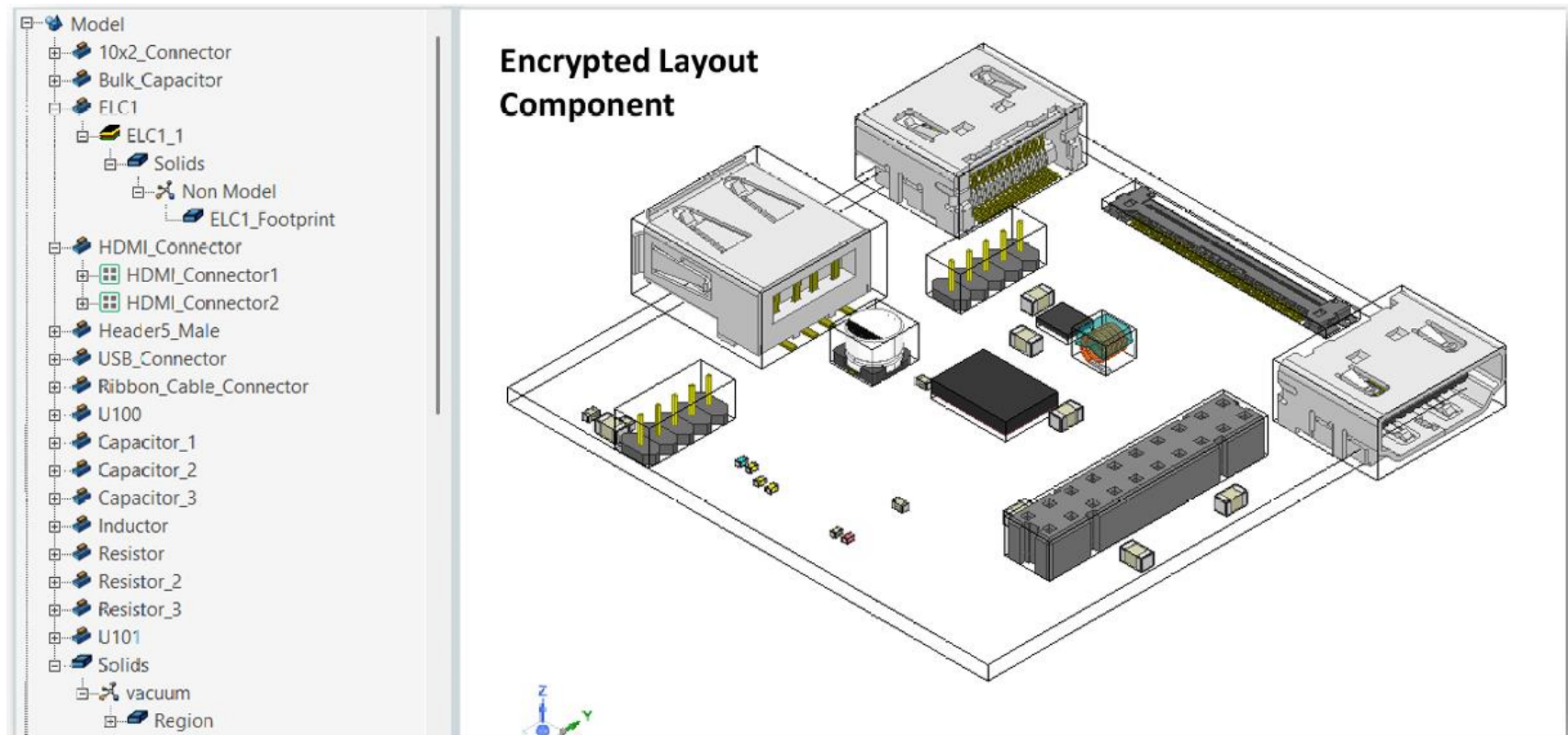


2026R1



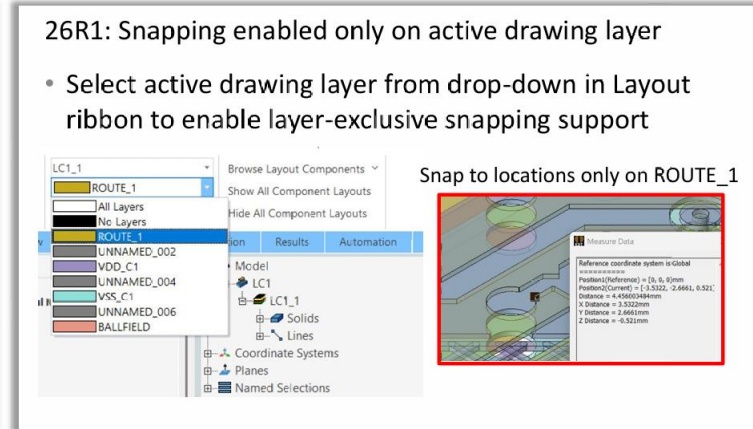
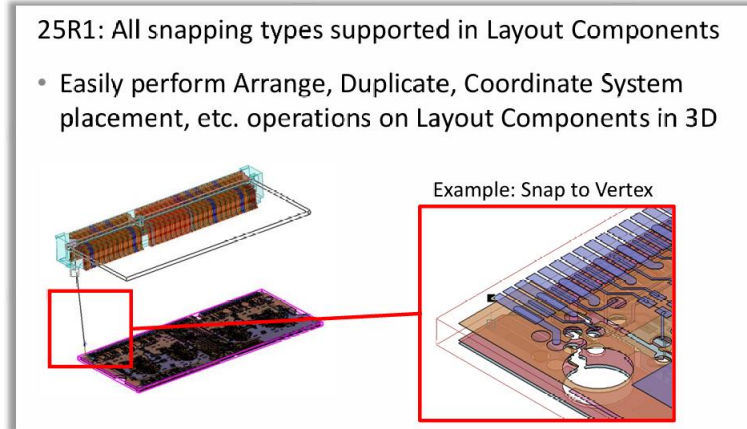
## 2026 R1 추가 기능

- ✓ Encrypted layout components
  - Component의 내부 형상을 보이지 않도록 암호화
  - Materials과 stack-up도 암호화하여 공유 가능함

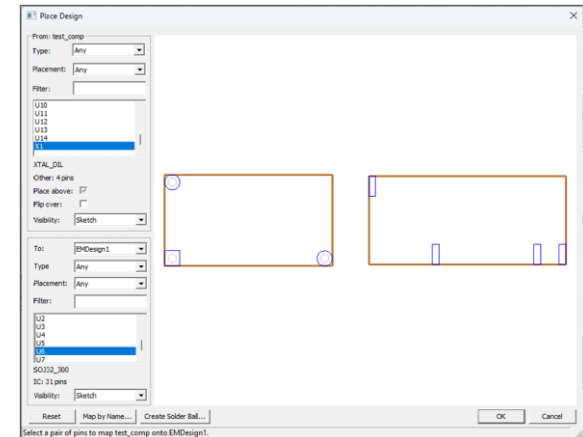


## 2026 R1 추가 기능

- ✓ Active layer setting to enable snapping support
  - 3D modeler UI 속도 개선
  - 선택된 Active layer에 대한 snap 기능 추가



- ✓ 참고: 3D layout design과 layout component는 place design과 pin connectivity window에서 서로 연결되는 pin을 선택하면 자동으로 component 위치 지정이 가능함

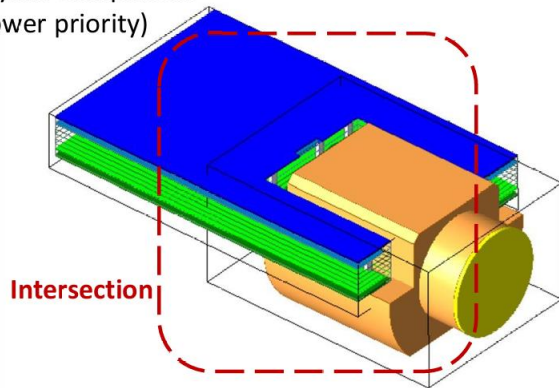


## 2026 R1 추가 기능

- ✓ HFSS 3D:
  - Layout component와 3D component의 물리적 간섭이 허용되고 겹치는 부분의 우선 순위 설정이 가능함
- ✓ HFSS 3D layout: TAU mesher enabled
  - Mesh fusion 기능으로 각 component의 mesher 선택 가능함

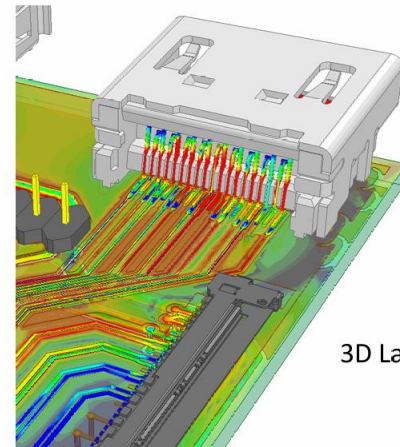
HFSS 3D: intersection is automatically resolved for encrypted components with higher priority in mesh fusion workflow

Layout Component  
(lower priority)



Encrypted SMA Connector  
(higher priority)

HFSS 3D Layout: TAU mesher option is now enabled for 3D Components in 3D Layout mesh fusion workflow



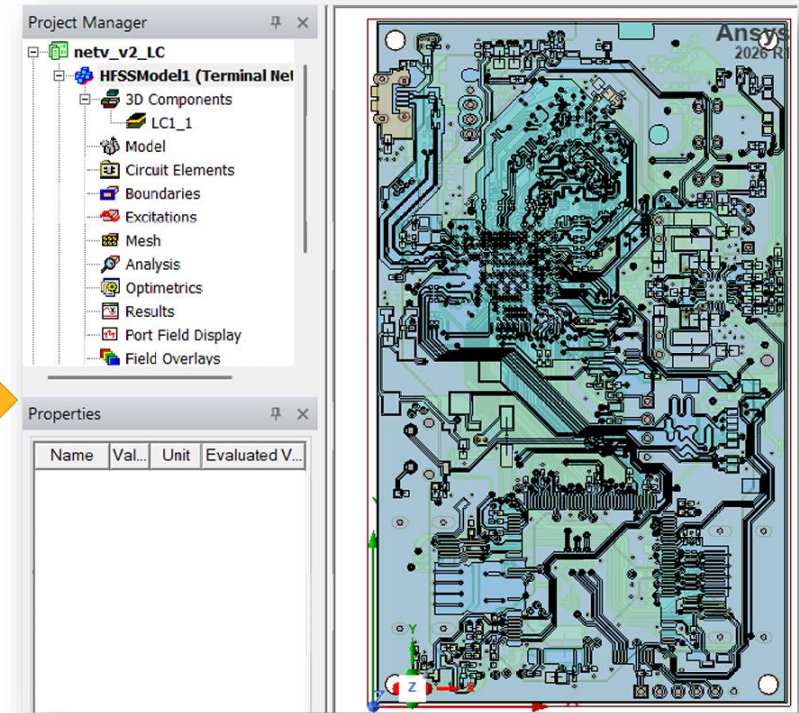
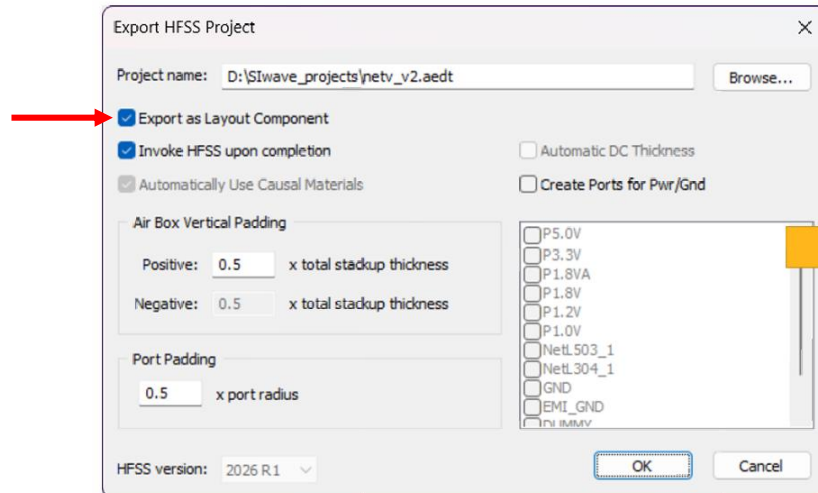
3D Component  
Connector (TAU)

3D Layout (Phi)

## 2026 R1 추가 기능

✓ SIwave에서 layout component 생성이 가능함

- Layout Component export by default

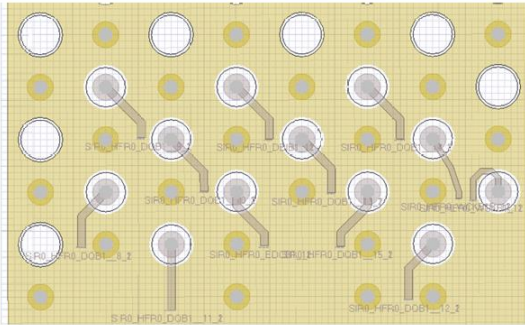


## 2026 R1 추가 기능

- ✓ SIwave HFSS Region
- ✓ 사용자 지정 trace 길이를 추가한 Region 생성

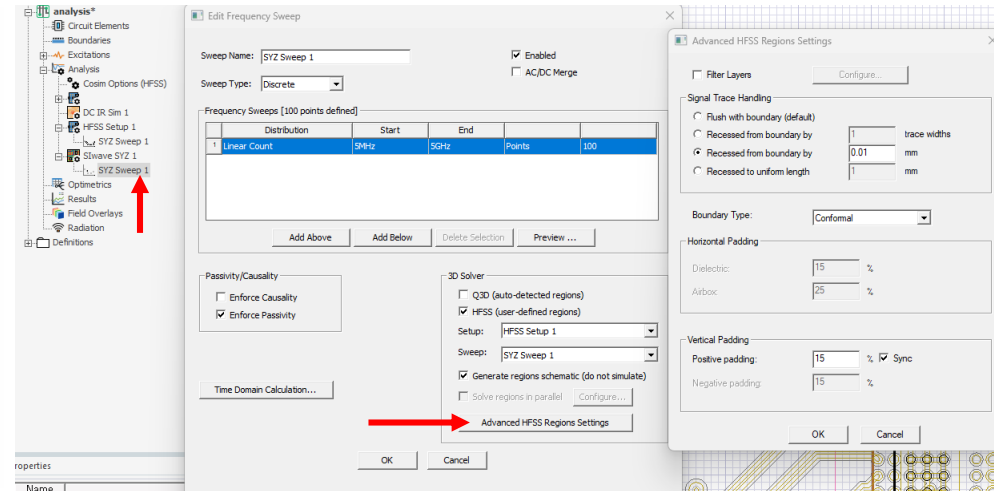
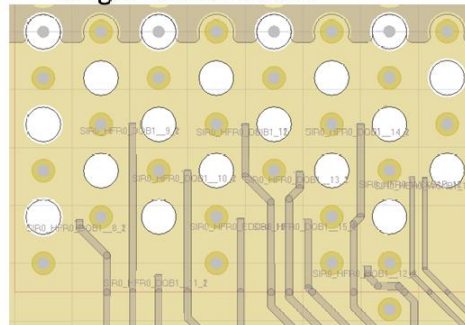
### HFSS Geometry

- Traces recessed from boundary to ensure each route is 1mm long



### SIwave Geometry

- Traces extended into boundary to ensure each route's total length is unaffected

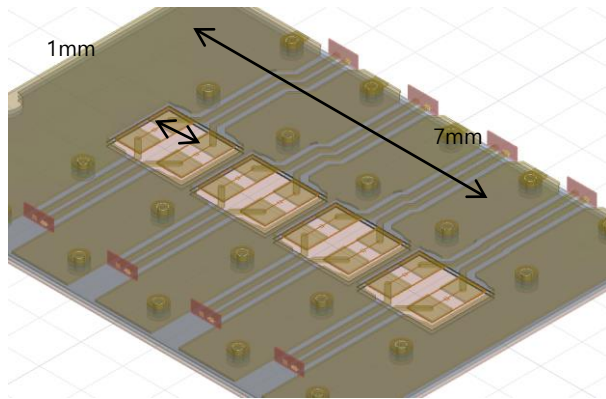


## ■ 목차

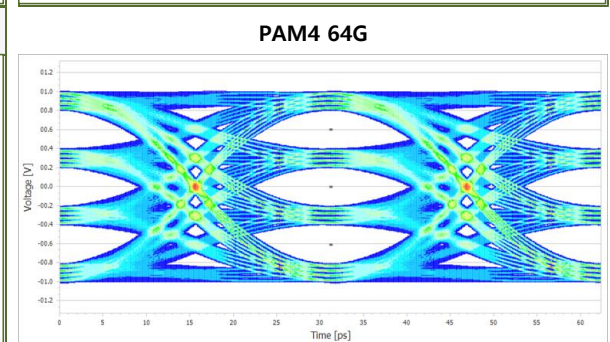
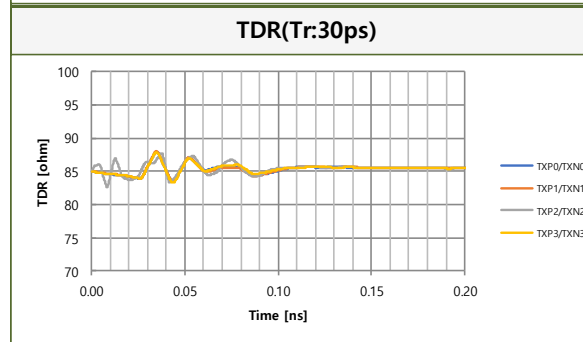
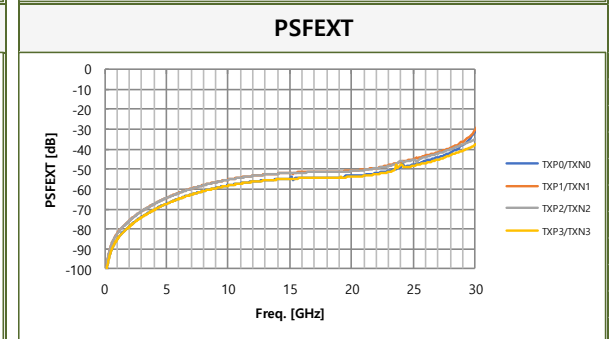
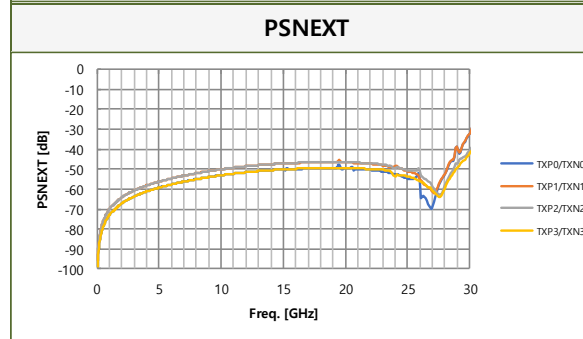
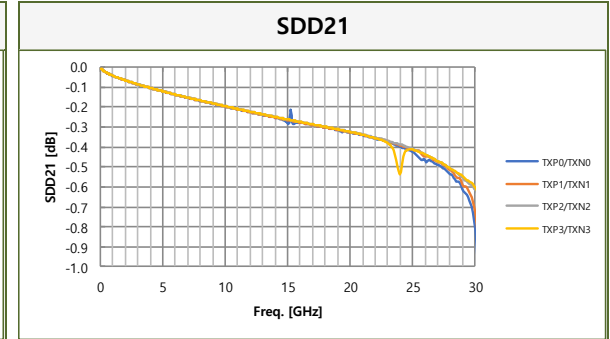
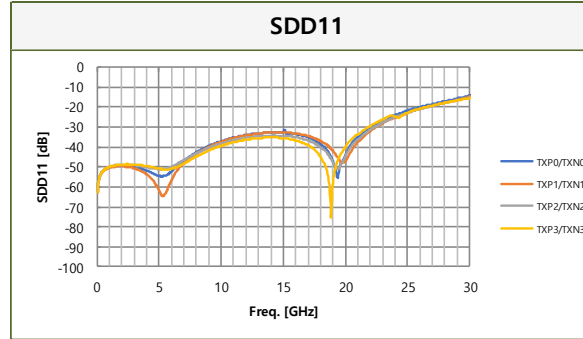
1. Ansys EM 2026 R1 SI 추가 기능
2. 3D Component 활용 사례

## 3D component 활용 사례

- ✓ Case1: Ideal cap, matched
  - ✓ 간격: 1mm
  - ✓ 전체 폭: 7mm



Part Type:	Capacitor
Ref Des:	C2650
No. Pins:	2
<input checked="" type="checkbox"/> Enabled	
Model Info	
Type:	RLC network
Pin One	Pin Two
2	1
Name	
Layer	TOP
Type	Series
EnableR	<input type="checkbox"/>
EnableL	<input type="checkbox"/>
EnableC	<input checked="" type="checkbox"/>
C	2.2e-07rad

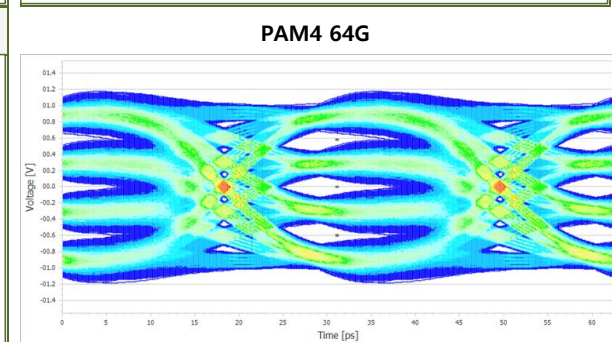
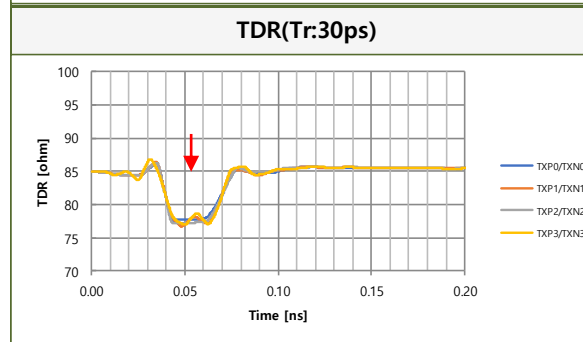
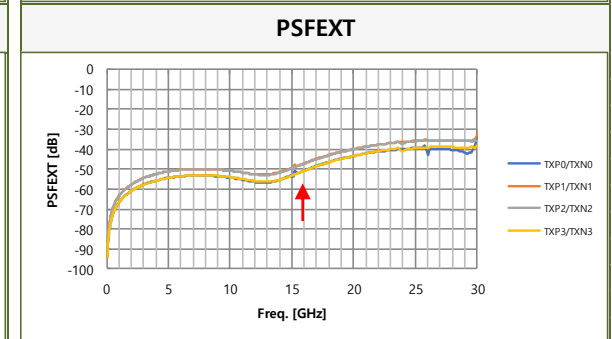
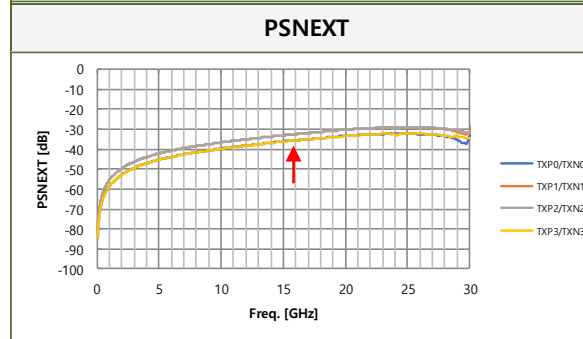
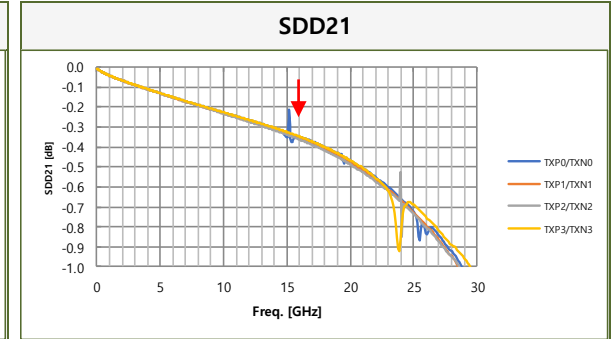
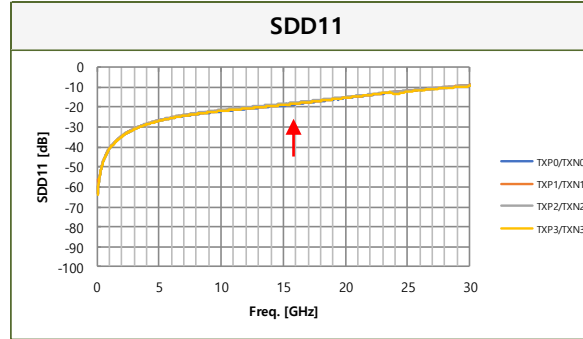
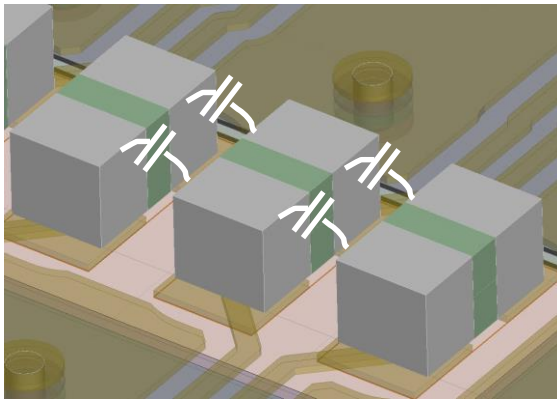
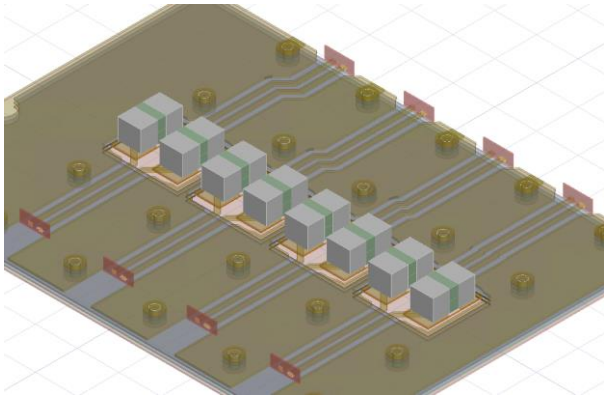


Net Name	SDD11	SDD21	PSNEXT	PSFEXT
TXP1/TXN1	-33.20	-0.28	-46.88	-51.61

Width upper (ps)	Height upper (mv)	Width center (ps)	Height center (mv)	Width lower (ps)	Height lower (mv)
14.87	398.99	18.12	403.42	14.5	403.42

## 3D component 활용 사례

- ✓ Case2: 3D cap
  - ✓ Case1 PCB에 3D comp.로 변경
  - ✓ TDR 임피던스 ↓
  - ✓ X-talk ↑
  - ✓ Eye ↓

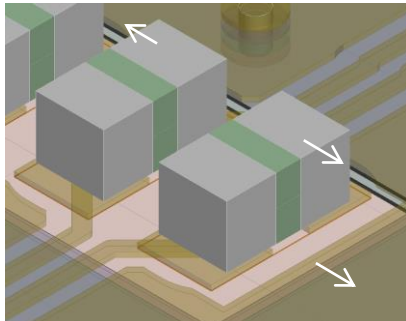
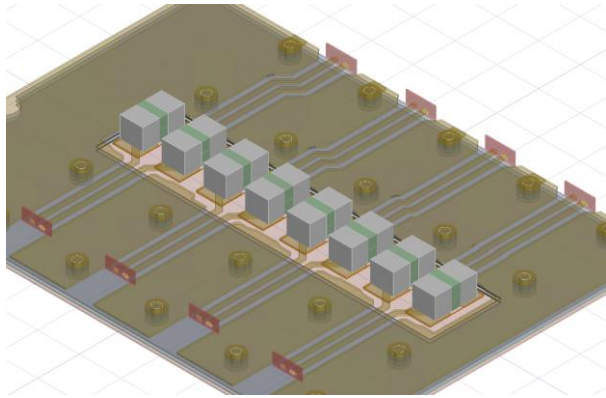


Net Name	SDD11	SDD21	PSNEXT	PSFEXT
TXP1/TXN1	-18.160	-0.355	-32.427	-47.065

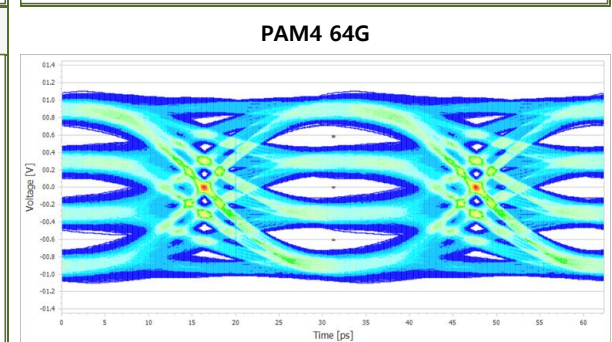
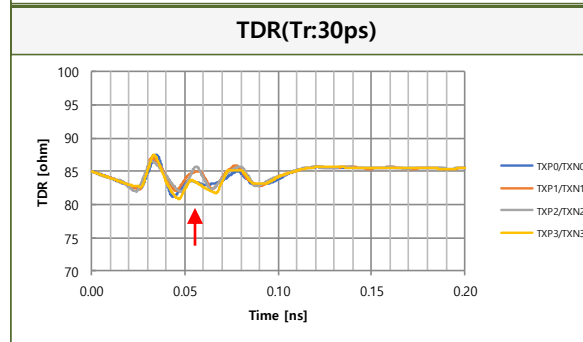
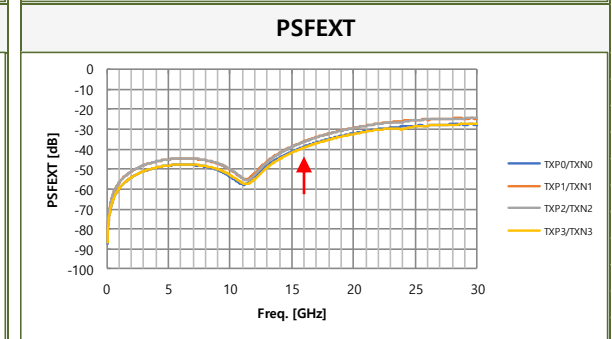
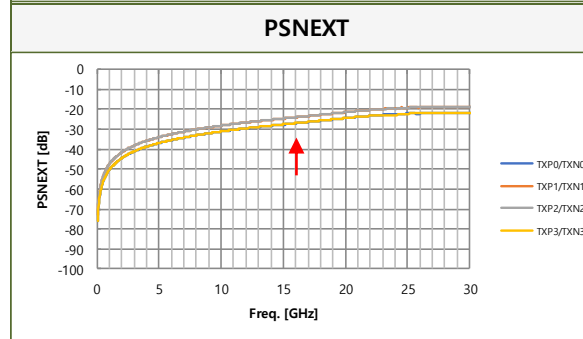
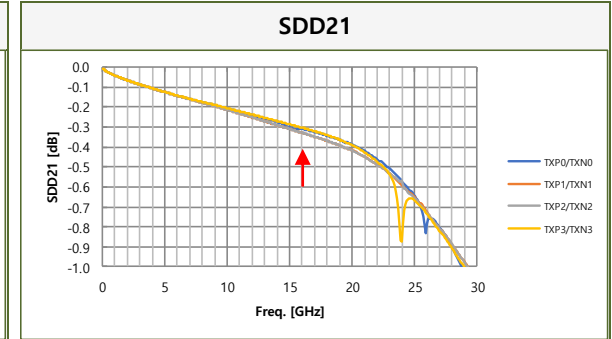
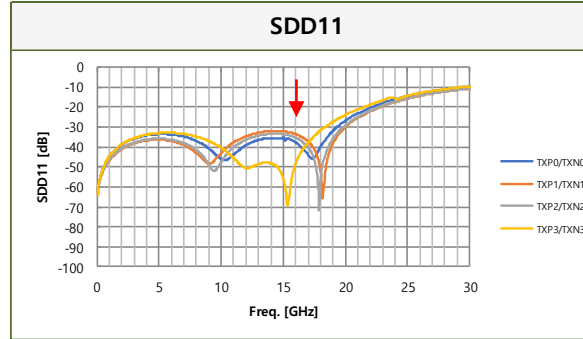
Width upper (ps)	Height upper (mv)	Width center (ps)	Height center (mv)	Width lower (ps)	Height lower (mv)
8.37	145.49	12.63	176.66	10.62	161.08

## 3D component 활용 사례

- ✓ Case3: 3D cap, matched
  - ✓ Case2 PCB를 최적화
  - ✓ TDR 임피던스 ↑
  - ✓ X-talk ↓
  - ✓ Eye ↑



Cap 간격 ↑ 임피던스 ↓  
 Void 영역 ↑ 임피던스 ↑

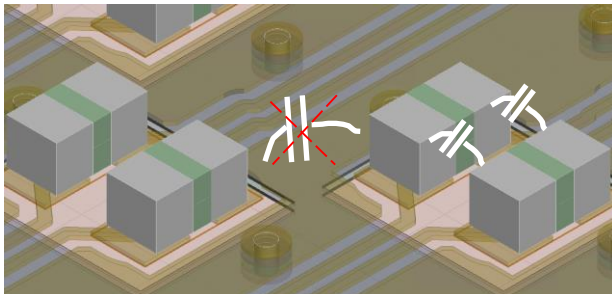
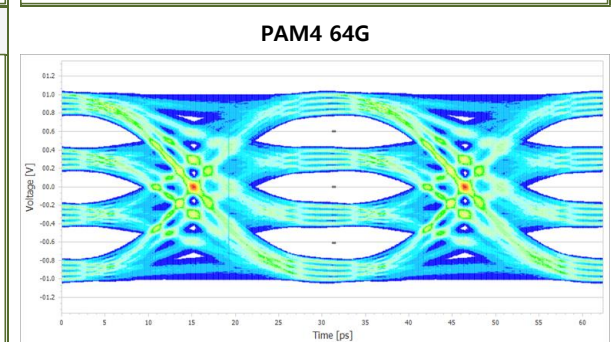
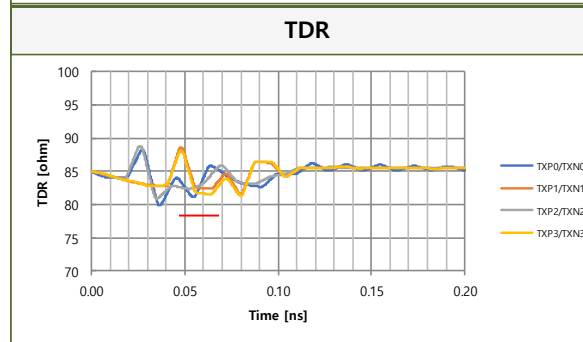
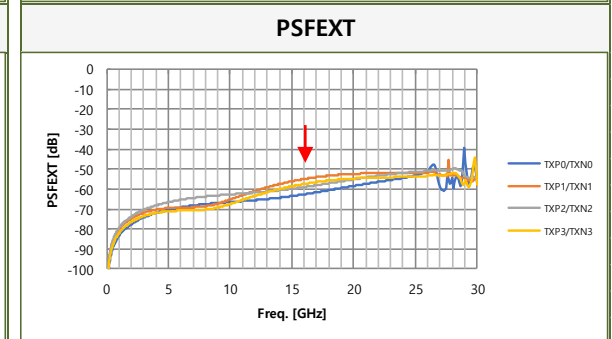
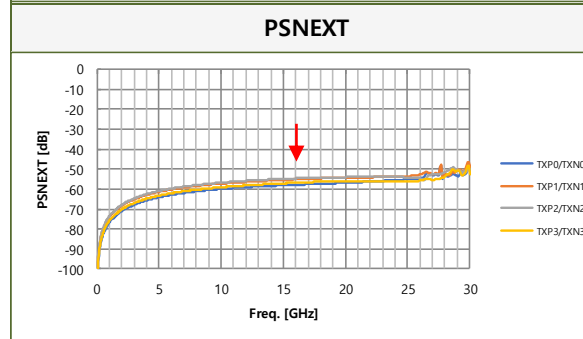
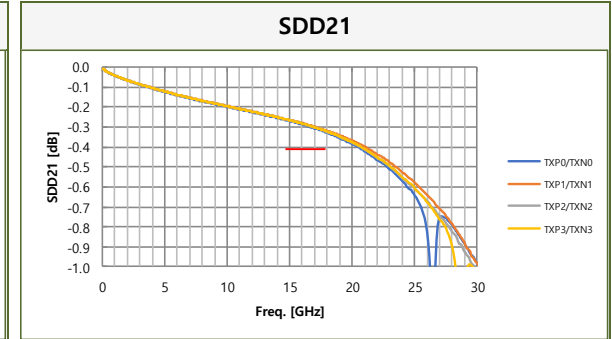
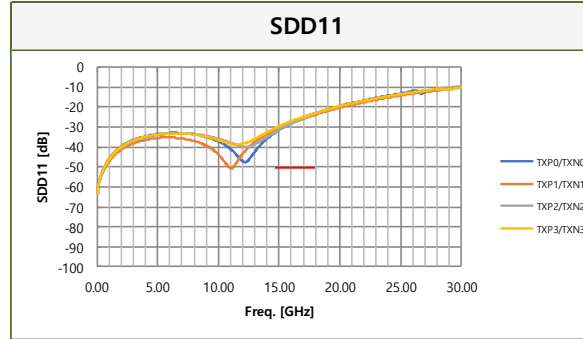
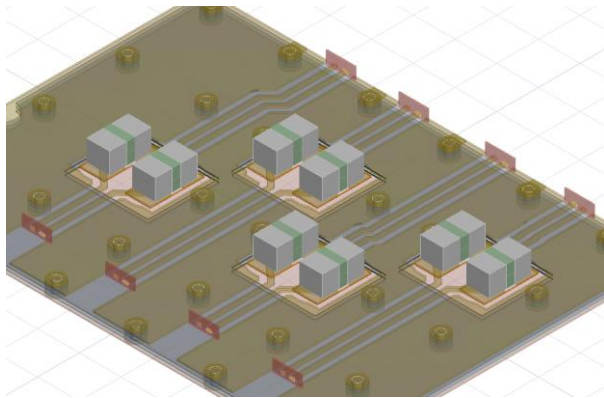


Net Name	SDD11	SDD21	PSNEXT	PSFEXT
TXP1/TXN1	-33.55	-0.33	-24.02	-36.09

Width upper (ps)	Height upper (mv)	Width center (ps)	Height center (mv)	Width lower (ps)	Height lower (mv)
12.63	232.25	15.25	217.74	12.25	227.41

## 3D component 활용 사례

- ✓ Case4: 3D cap, matched, zigzag
  - ✓ Case3 cap 배치 변경
  - ✓ TDR 임피던스 ↔
  - ✓ X-talk ↓
  - ✓ Eye ↑



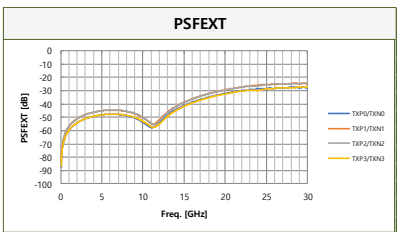
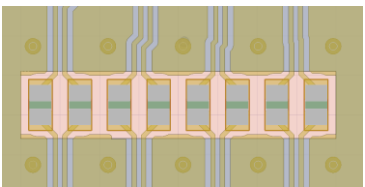
Net Name	SDD11	SDD21	PSNEXT	PSFEXT
TXP1/TXN1	-27.869	-0.280	-55.152	-54.935

Width upper (ps)	Height upper (mv)	Width center (ps)	Height center (mv)	Width lower (ps)	Height lower (mv)
15.12	338.03	18.25	342.59	15	347.16

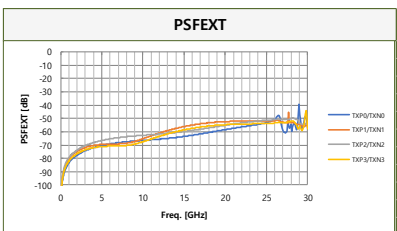
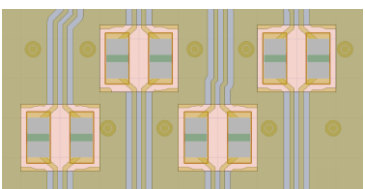
## 3D component 활용 사례

- ✓ 요약
  - ✓ 패키지를 고려하지 않은 ideal 소자로 최적화된 PCB는 3D component를 이용한 분석 결과와 차이가 큼
  - ✓ 여러 net으로 구성된 채널 분석은 cross-talk를 반영하는 time domain 분석이 필요함
  - ✓ 레이아웃 밀도가 높아지고 통합이 가속화되고 있는 환경에서 3D component를 이용한 PCB와 부품의 영향 분석 및 layout component를 이용한 PCB와 패키지 등의 복잡한 커플링을 고려한 분석이 요구됨
  - ✓ 채널 구성 요소를 따로 해석 후 연결하여 간편하고 빠르게 분석 가능하지만, 각 component 간의 커플링이 고려되지 않아 잘못된 평가가 될 수 있음

SDD11	SDD21	PSNEXT	PSFEXT	Width upper (ps)	Height upper (mv)	Width center (ps)	Height center (mv)	Width lower (ps)	Height lower (mv)
-33.20	-0.28	-46.88	-51.61	14.87	398.99	18.12	403.42	14.5	403.42
SDD11	SDD21	PSNEXT	PSFEXT	Width upper (ps)	Height upper (mv)	Width center (ps)	Height center (mv)	Width lower (ps)	Height lower (mv)
-18.160	-0.355	-32.427	-47.065	8.37	145.49	12.63	176.66	10.62	161.08
SDD11	SDD21	PSNEXT	PSFEXT	Width upper (ps)	Height upper (mv)	Width center (ps)	Height center (mv)	Width lower (ps)	Height lower (mv)
-33.55	-0.33	-24.02	-36.09	12.63	232.25	15.25	217.74	12.25	227.41
SDD11	SDD21	PSNEXT	PSFEXT	Width upper (ps)	Height upper (mv)	Width center (ps)	Height center (mv)	Width lower (ps)	Height lower (mv)
-27.869	-0.280	-55.152	-54.935	15.12	338.03	18.25	342.59	15	347.16

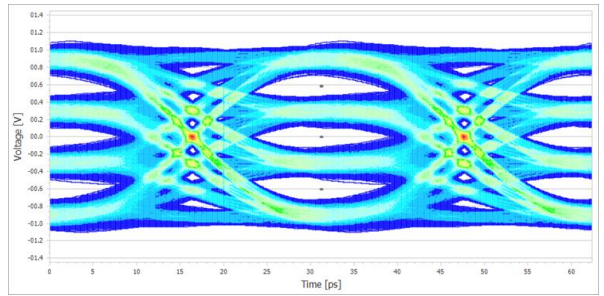


PSNEXT	PSFEXT
-24.02	-36.09



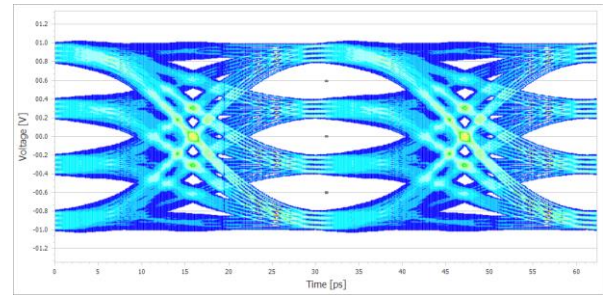
PSNEXT	PSFEXT
-55.152	-54.935

PAM4 64G X-talk on

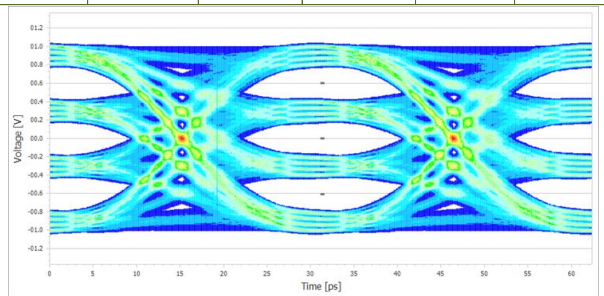


Width upper (ps)	Height upper (mv)	Width center (ps)	Height center (mv)	Width lower (ps)	Height lower (mv)
12.63	232.25	15.25	217.74	12.25	227.41

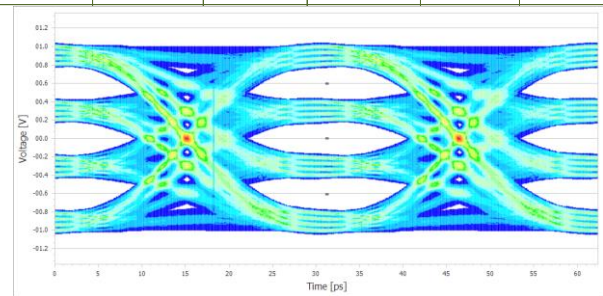
PAM4 64G X-talk off



Width upper (ps)	Height upper (mv)	Width center (ps)	Height center (mv)	Width lower (ps)	Height lower (mv)
15	373.08	18.12	373.08	14.87	373.08



Width upper (ps)	Height upper (mv)	Width center (ps)	Height center (mv)	Width lower (ps)	Height lower (mv)
15.12	338.03	18.25	342.59	15	347.16



Width upper (ps)	Height upper (mv)	Width center (ps)	Height center (mv)	Width lower (ps)	Height lower (mv)
15.25	342.92	18.37	342.92	15	342.92

## HFSS vs HFSS 3D layout

- ✓ HFSS
  - ✓ 물리적인 형상과 재질만 존재하여 임의의 모든 형상 해석 가능함
  - ✓ 많은 자원이 필요하지만 신뢰도가 높음
  - ✓ 모든 구성요소를 자유롭게 편집 가능하지만 상대적으로 무거운 GUI가 불편함
- ✓ HFSS 3D Layout
  - ✓ 적층 구조에 최적화된 유저 인터페이스를 제공함
  - ✓ Net, stack-up, pad stack 등의 속성으로 편집이 매우 편리함
  - ✓ PCB 구조에 특화된 mesher 사용으로 속도가 빠름
- ✓ Layout & 3D component
  - ✓ 개체 내부를 직접 편집하기 어렵지만 GUI 반응속도가 빠르고 핸들링이 용이함
  - ✓ Mesh Fusion 기능으로 각 개체에 적합한 mesher 사용이 가능함
  - ✓ 암호화 기능으로 내부 구조 공개하지 않고 해석 모델 제공이 가능함